



SOT416

plastic surface-mounted package; 3 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SC-75
Package type industry code	SC-75
Package style descriptive code	SOT (small outline transistor)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEITA package outline code	SC-75
Mounting method type	S (surface mount)
Issue date	7-6-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.4	-	1.6	1.8	mm
E	package width	0.7	-	0.8	0.9	mm
A	seated height	0.6	-	0.75	0.9	mm
e	nominal pitch	-	-	1	-	mm
n ₂	actual quantity of termination	-	-	3	-	



2. Package outline

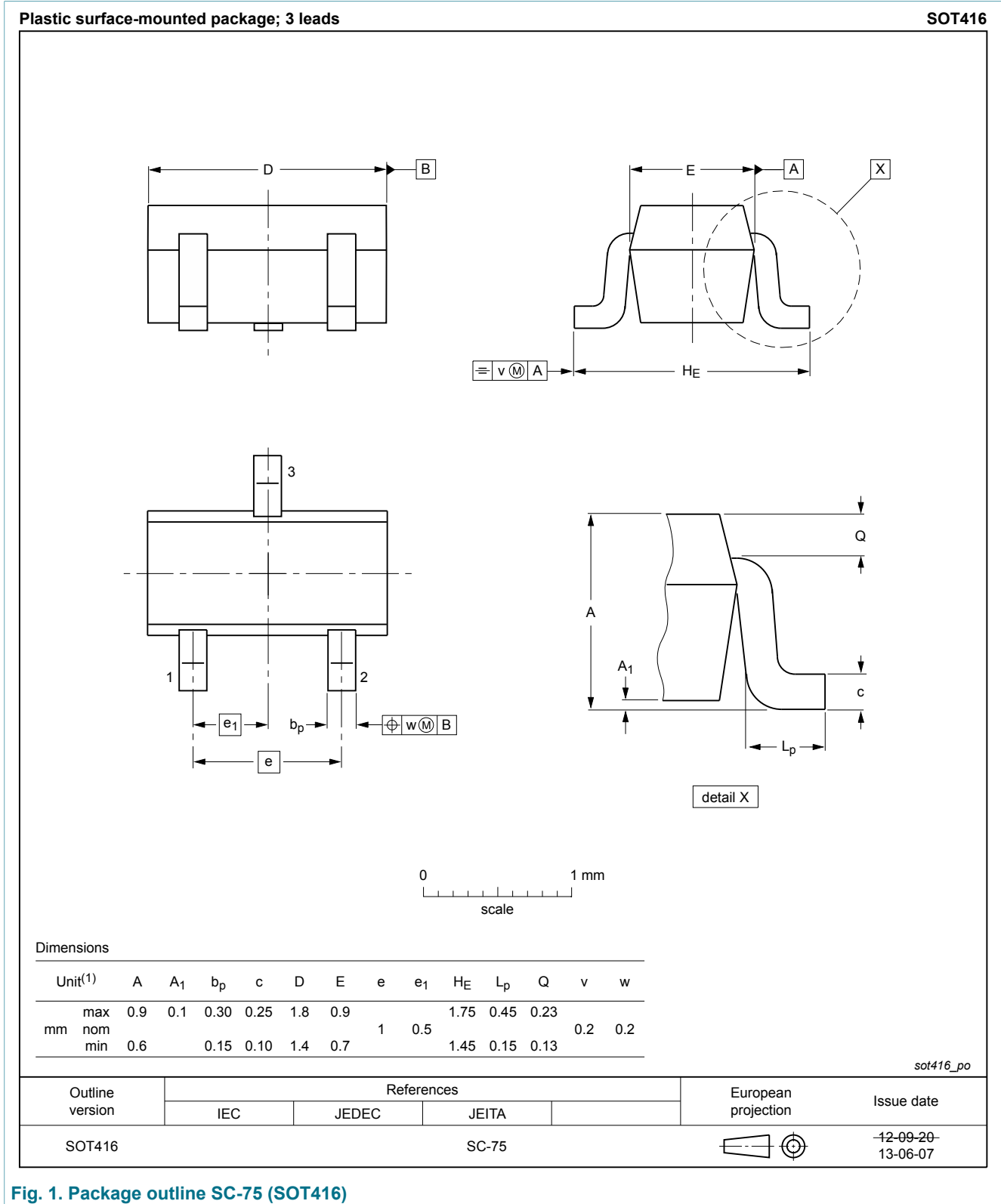


Fig. 1. Package outline SC-75 (SOT416)

3. Soldering

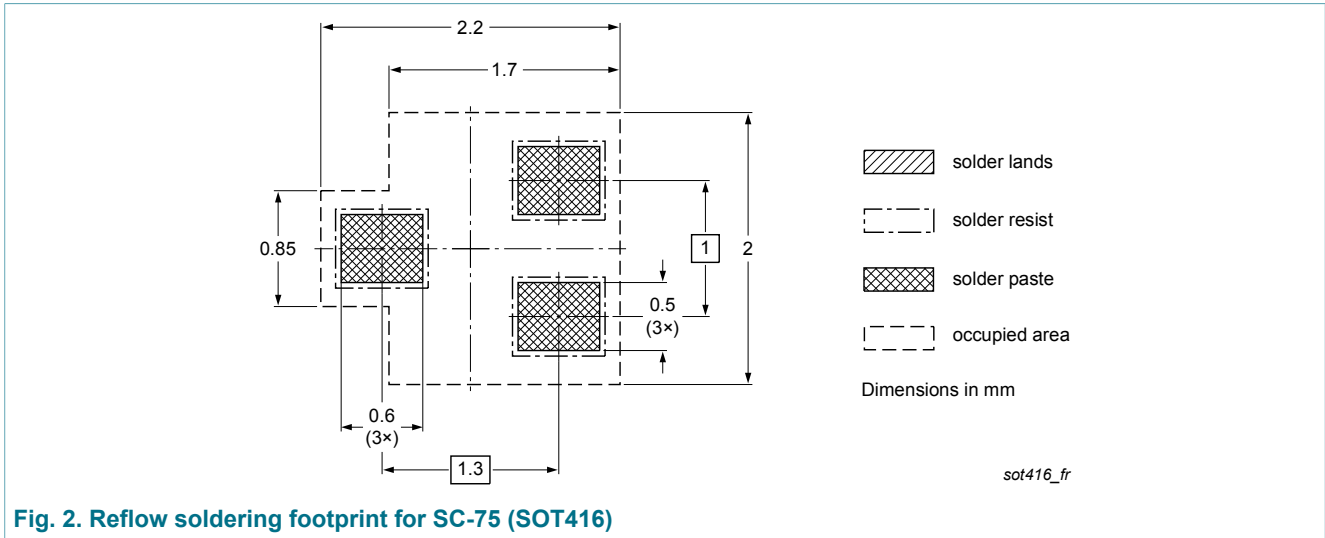


Fig. 2. Reflow soldering footprint for SC-75 (SOT416)

4. Legal information

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